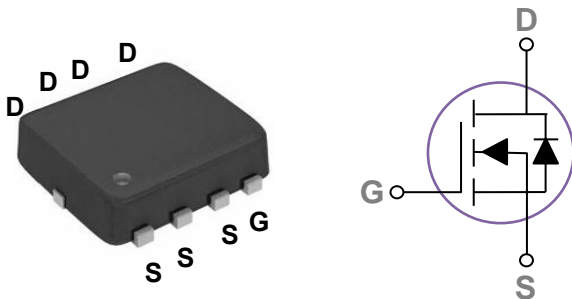


40V N-Channel MOSFETs

General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

PPAK3×3 Pin Configuration



BV_{DSS}	$R_{DS(ON)Max.}$	I_D
40V	5.5m Ω	50A

Features

- 40V, 50A, $R_{DS(ON)Max.}=5.5m\Omega@V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

Applications

- Notebook
- Load Switch
- LED applications
- Hand-Held Device

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	50	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	31	A
I_{DM}	Drain Current – Pulsed ¹	240	A
E_{AS}	Single Pulse Avalanche Energy ²	76	mJ
I_{AS}	Single Pulse Avalanche Current ²	39	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	66	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Note 1: Exceed these limits to damage to the device.

Note 2: Exposure to absolute maximum rating conditions may affect device reliability.

Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise

noted) Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	40			V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=40V, V_{GS}=0V, T_J=25^\circ C$			1	μA
		$V_{DS}=32V, V_{GS}=0V, T_J=85^\circ C$			10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=24A$		4.8	5.5	$m\Omega$
		$V_{GS}=4.5V, I_D=12A$		6.2	7.2	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.6	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient			-4		$mV/^\circ C$
g_{fs}	Forward Transconductance	$V_{DS}=5V, I_D=20A$		70		S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{3, 4}	$V_{DS}=20V, V_{GS}=10V, I_D=15A$		27.8		nC
Q_{gs}	Gate-Source Charge ^{3, 4}			3.9		
Q_{gd}	Gate-Drain Charge ^{3, 4}			6		
$T_{d(on)}$	Turn-On Delay Time ^{3, 4}	$V_{DD}=15V, V_{GS}=10V, R_G=3.3\Omega$ $I_D=1A$		7.2		ns
T_r	Rise Time ^{3, 4}			3		
$T_{d(off)}$	Turn-Off Delay Time ^{3, 4}			23		
T_f	Fall Time ^{3, 4}			3.5		
C_{iss}	Input Capacitance	$V_{DS}=20V, V_{GS}=0V, F=1MHz$		1830		pF
C_{oss}	Output Capacitance			521		
C_{rss}	Reverse Transfer Capacitance			43		
R_g	Gate resistance	$V_{GS}=0V, V_{DS}=0V, F=1MHz$		0.8		Ω

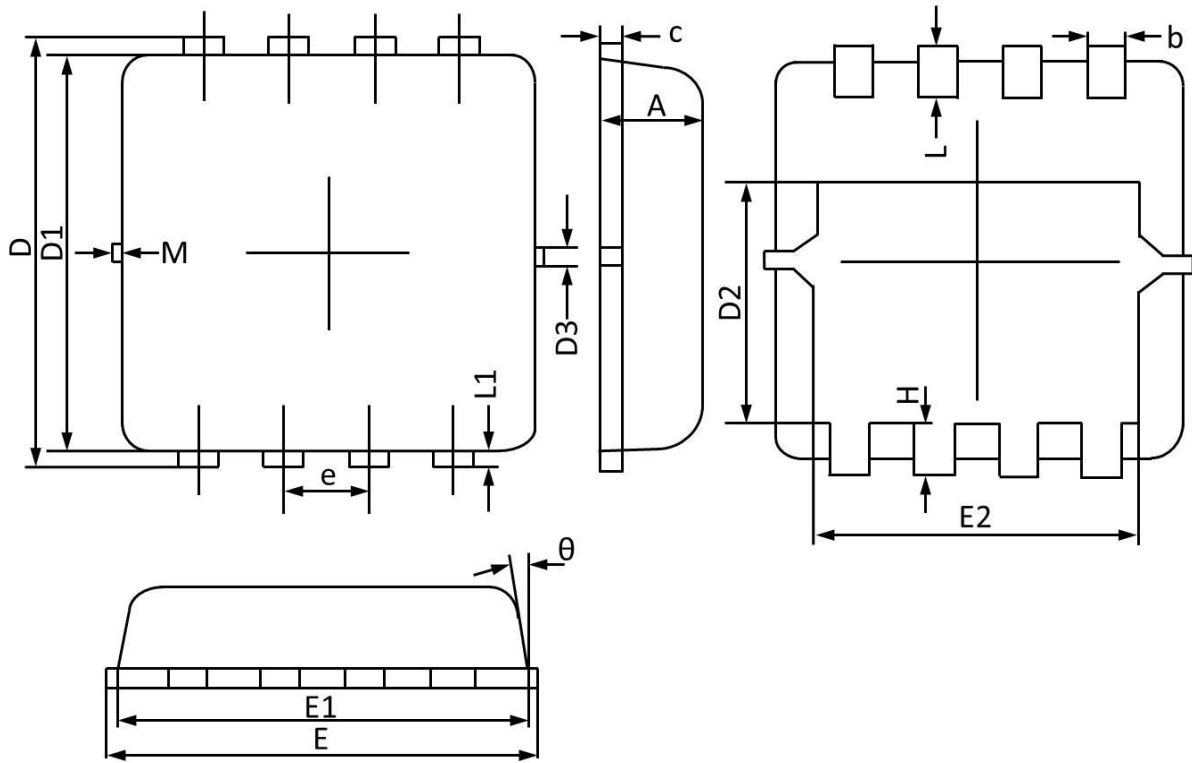
Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G=V_D=0V, \text{ Force Current}$			50	A
I_{SM}	Pulsed Source Current				100	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V, I_S=1A, T_J=25^\circ C$			1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=39A, R_G=25\Omega, \text{ Starting } T_J=25^\circ C$.
3. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

PPAK3x3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.800	0.028	0.031
b	0.250	0.350	0.010	0.013
c	0.100	0.250	0.004	0.009
D	3.250	3.450	0.128	0.135
D1	3.000	3.200	0.119	0.125
D2	1.780	1.980	0.070	0.077
D3	0.130 REF		0.005 REF	
E	3.200	3.400	0.126	0.133
E1	3.000	3.200	0.119	0.125
E2	2.390	2.590	0.094	0.102
e	0.650 BSC		0.026 BSC	
H	0.300	0.500	0.011	0.019
L	0.300	0.500	0.011	0.019
L1	0.130 REF		0.005 REF	
θ	0°	12°	0°	12°
M	0.150 REF		0.006 REF	